

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION

Generic Copy

11 Jul 2008

SUBJECT: ON Semiconductor Final Product/Process Change Notification #16131

TITLE: Final Notification of Qualification of SP Semiconductor site at Korea for the Assembly and Test of Bipolar Power Transistors in Isolated TO220 package.

PROPOSED FIRST SHIP DATE: 12 Oct 2008

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Assembly & Test Site

AFFECTED PRODUCT DIVISION(S): Standard Components

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or Jose Ramirez < jose.l.ramirez@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Laura Rivers < laura.rivers@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is the FPCN to IPCN16025 that announced the planned capacity expansion of ON Semiconductor assembly and test operations for Bipolar Power Transistors in Isolated TO-220 package, currently build at the PSI Manila facility, to SP Semiconductor's Korea facility. Upon the expiration of this FPCN, these devices may be processed at either location. The SP Semiconductor facility is ISO/TS 16949:2002 certified.

The SP Semiconductor package has 2 ejector pin holes approx 30 mils deep located at the front tab area beneath the mounting hole. The isolation voltage will be tested at 4.6KV 0.3 Sec at the bottom of the package.

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RELIABILITY DATA SUMMARY:

Reliability Test Results:

ELECTRICAL CHARACTERISTIC SUMMARY:

There is no change in electrical characteristics. Characterization Data is available upon request.

CHANGED PART IDENTIFICATION:

Product from SP Semiconductor will be identified by SP site code marking.

AFFECTED DEVICE LIST:

MJF122G

MJF127G

MJF15030G

MJF15031G

MJF2955G

MJF3055G

MJF31CG

MJF32CG

MJF44H11G

MJF45H11G

MJF6388G

MJF6668G

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